Title (en)

COPPER-ZINC ALLOY ELECTROPLATING BATH AND PLATING METHOD USING THE COPPER-ZINC ALLOY ELECTROPLATING BATH

Title (de)

GALVANISIERUNGSBAD AUS KUPFER-ZINK-LEGIERUNG UND PLATTIERUNGSVERFAHREN MIT DEM GALVANISIERUNGSBAD AUS KUPFER-ZINK-LEGIERUNG

Title (fr)

BAIN D'ÉLECTRODÉPOSITION D'ALLIAGE CUIVRE-ZINC ET PROCÉDÉ DE DÉPOSITION UTILISANT LE BAIN D'ÉLECTRODÉPOSITION D'ALLIAGE CUIVRE-ZINC

Publication

**EP 2218804 A1 20100818 (EN)**

Application

**EP 08854020 A 20081126**

Priority

- JP 2008071470 W 20081126
- JP 2007304377 A 20071126
- JP 2007304376 A 20071126

Abstract (en)

A cyanide-free copper-zinc alloy electroplating bath is provided which can form a uniform and glossy alloy layer having the desired composition even at a higher current density than that for a conventional electroplating bath, and which is excellent in productivity. The copper-zinc alloy electroplating bath comprises at least one selected from a copper salt, zinc salt, alkali metal pyrophosphate, and amino acid or a salt thereof, and has a pH of 8.5 to 14. The pH is preferably 10.5 to 11.8; and the concentration of the amino acid or a salt thereof is preferably 0.08 mol/L to 0.22 mol/L, more preferably 0.1 mol/L to 0.13 mol/L. As the amino acid or a salt thereof, histidine or a salt thereof may be preferably used.

IPC 8 full level

**C25D 3/58** (2006.01)

CPC (source: EP US)

**C25D 3/58** (2013.01 - EP US); C25D 3/38 (2013.01 - EP US)

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Designated extension state (EPC)

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DOCDB simple family (publication)

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